

# *Inverse Design in Silicon Nitride Photonics*

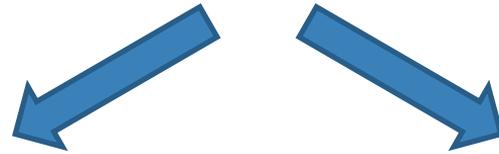
**Michaël Ménard**, Julian L. Pita Ruiz,  
Narges Dalvand

OPTICS, October 29<sup>th</sup>, 2025

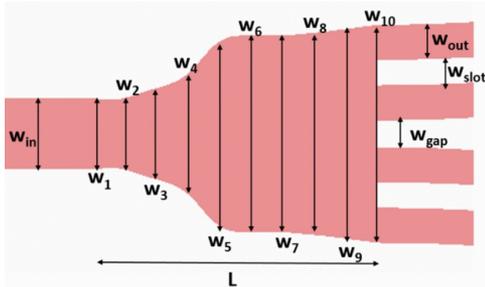


ÉCOLE DE  
TECHNOLOGIE  
SUPÉRIEURE  
Université du Québec

# Background—Inverse Design

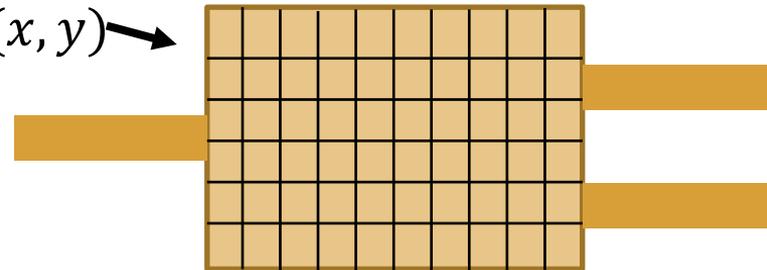


## Parametric (contour) Optimization



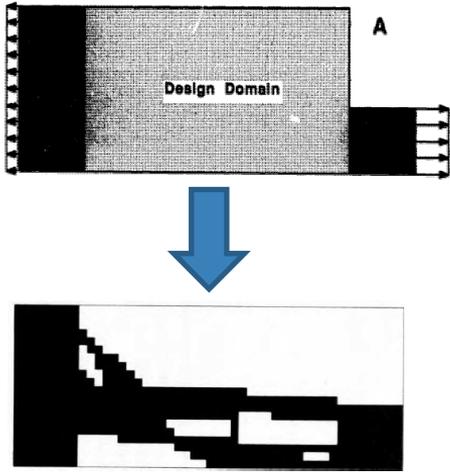
## Density Topology Optimization

$$\varepsilon(x, y)$$



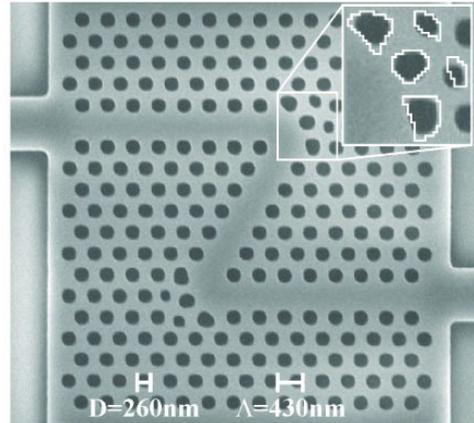
# Density Topology Optimization

## Mechanical Design



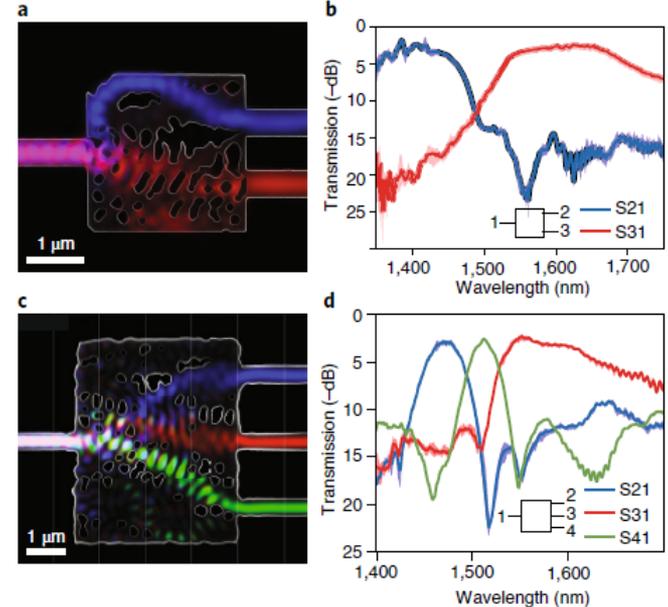
M. P. Bendsøe & N. Kikuchi,  
CMAME vol. 71 # 2, pp. 197-224  
(1988)

## 1<sup>st</sup> Demonstration in Integrated Photonics



P. I. Borel et. al. Opt. Express vol.  
12, pp. 1996-2001 (2004)

## General Formulation



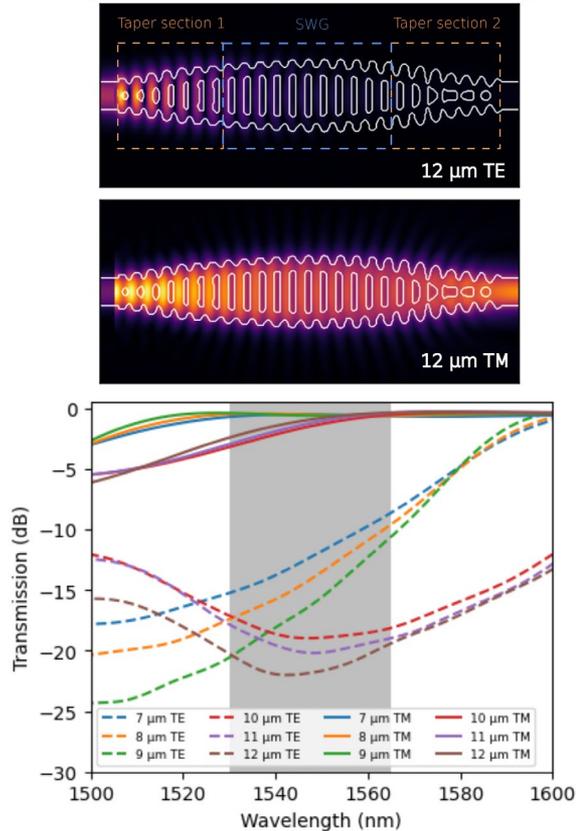
S. Molesky, Z. Lin, A.Y. Piggott, et al. Nature  
Photon vol. 12, pp. 659–670 (2018)

J. Vuckovic Proc. SPIE PC1360109 (2025)

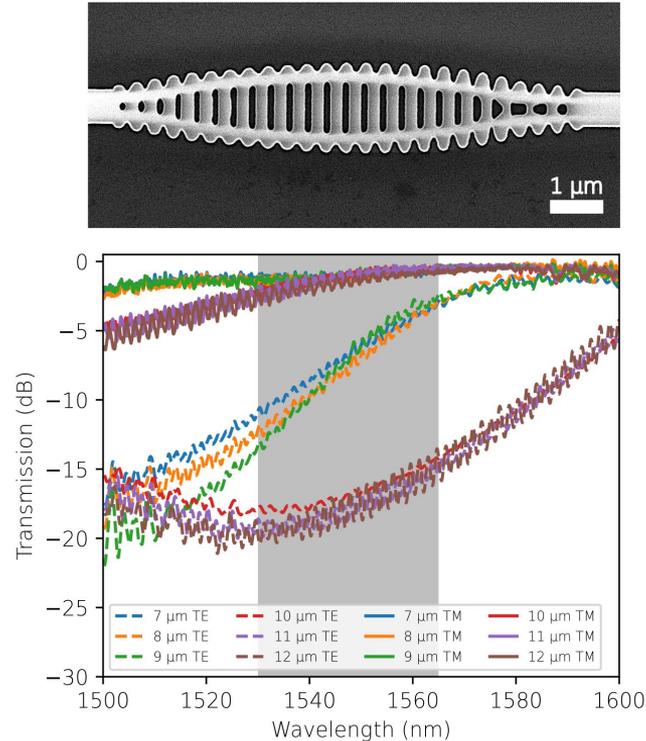
- Can we obtain compact high performance devices in SiN?
  - Polarizer
  - Coarse Wavelength Division Multiplexer (CWDM)
  - Spatial Mode Division Multiplexer (MDM)
  - Bimodal Mode Converter
  - Multi-mode Edge Coupler

# TM-Pass Polarizer

## Simulations



## Experiment



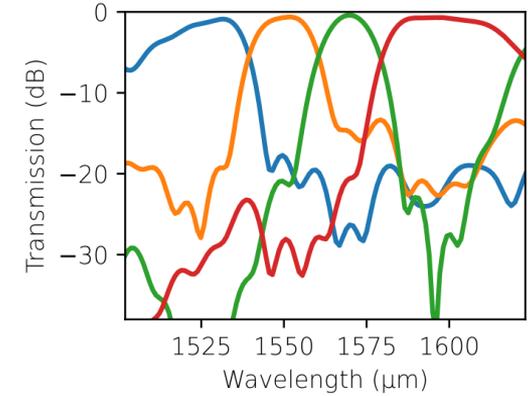
### Best device (11 $\mu\text{m} \times 2 \mu\text{m}$ ):

- TM insertion loss = **0.28 dB**
- PER = **18.2 dB**
- 3-dB bandwidth > 80 nm
- **Device area only 22  $\mu\text{m}^2$** , record-compact for SiN polarizers.
- Fabricated by Applied Nanotools on a 400 nm SiN platform

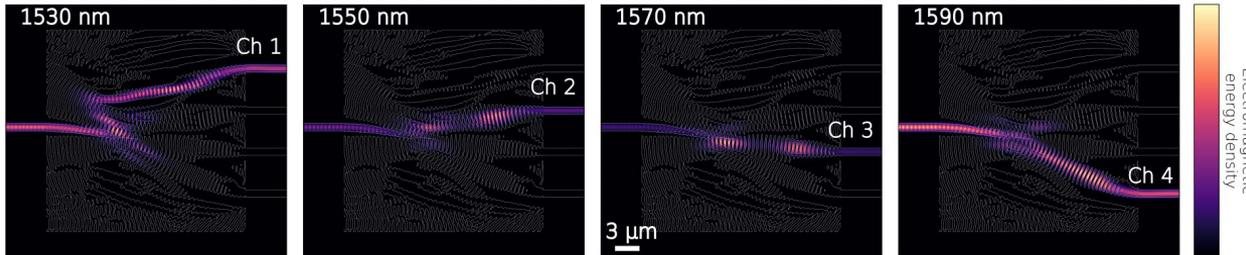
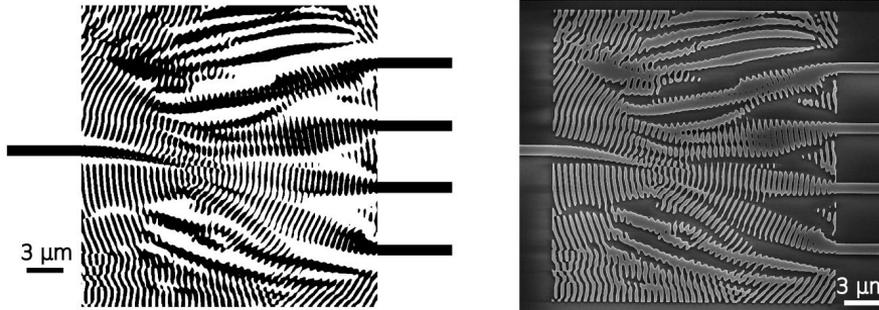
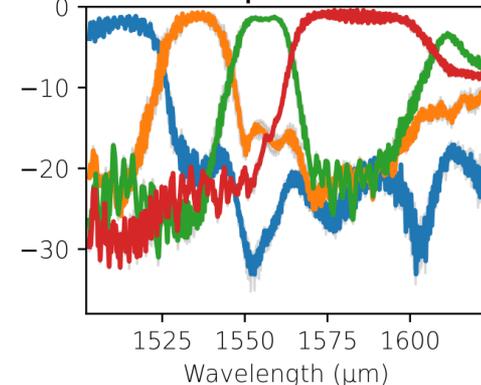
J. L. Pita Ruiz, F. Nabki, and M. Ménard, "Silicon nitride TM-pass polarizer using inverse design," Opt. Express 31, 37892-37899 (2023)

# Coarse Wavelength Division Multiplexer (CWDM)

## Simulations



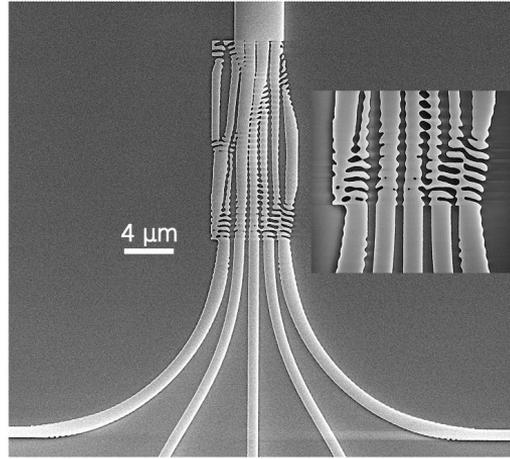
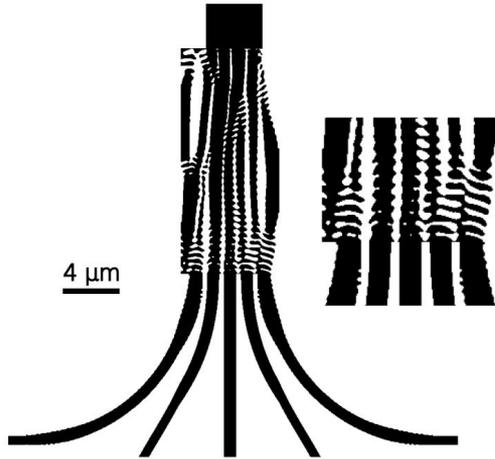
## Experiment



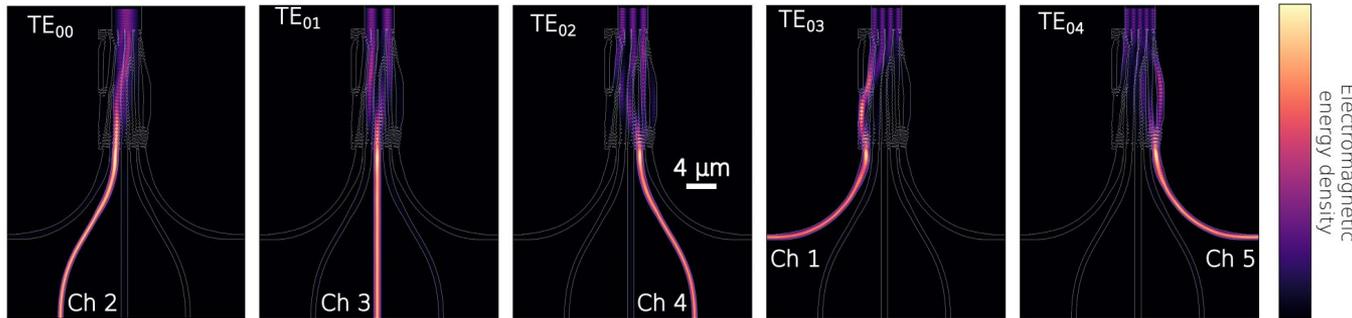
- Footprint  $24 \times 24 \mu\text{m}^2$
- Efficiency  $\approx -1$  dB per channel
- Crosstalk  $< -19$  dB

Pita Ruiz, N. Dalvand & M. Ménard "Integrated silicon nitride devices via inverse design." *Nat Commun* vol. 16, article 9307 (2025)

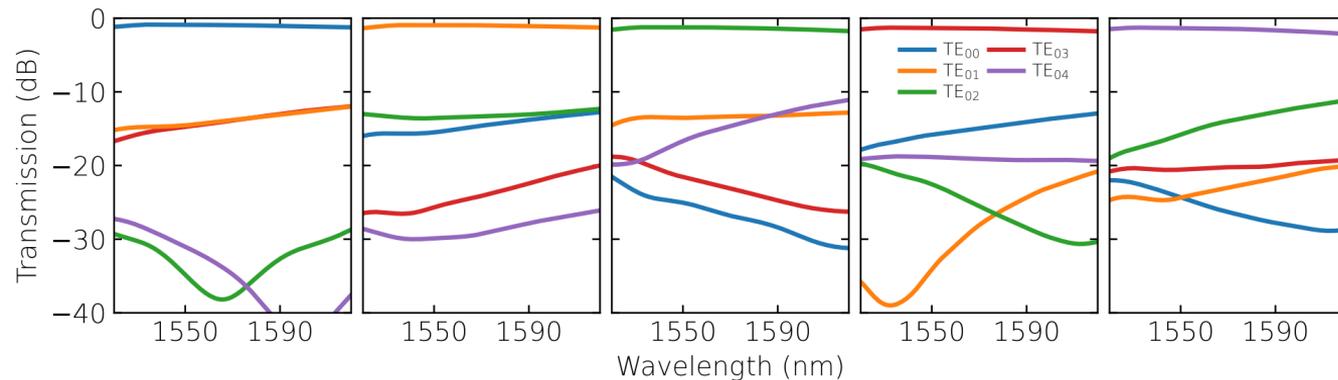
# 1 x 5 Spatial Mode Division Multiplexer (MDM)



- Footprint  $16 \times 7 \mu\text{m}^2$
- Convert between  $\text{TE}_{00}$ – $\text{TE}_{04}$  modes:

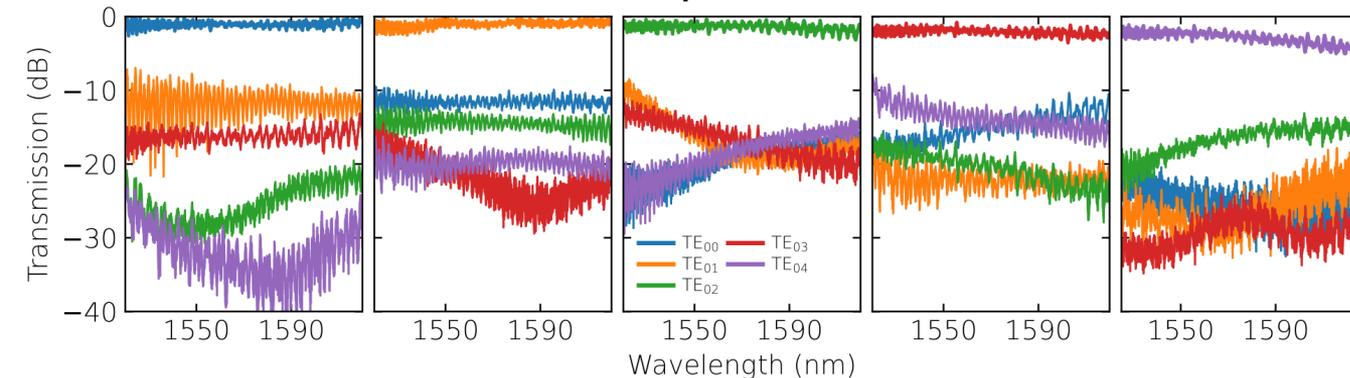


## Simulations



• Transmission: **-1 to -2.3 dB**

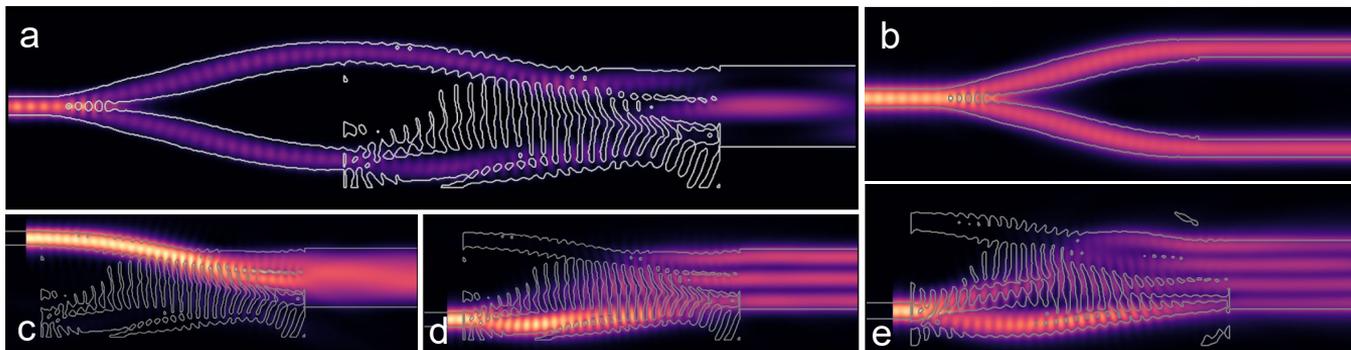
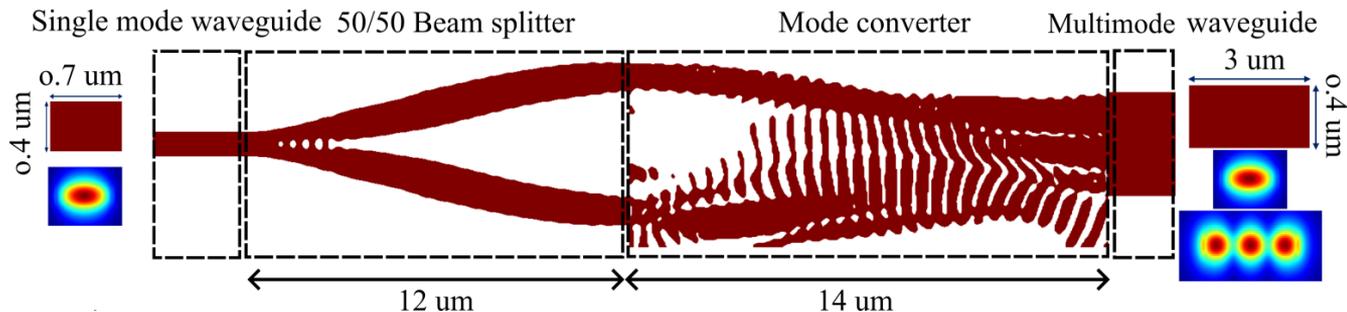
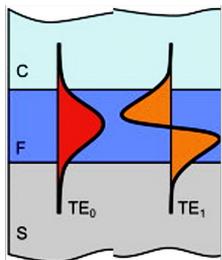
## Experiment



• Crosstalk: **-11 to -16 dB**

# Bimodal Mode Converter (BiMC)

## Bimodal Interferometer

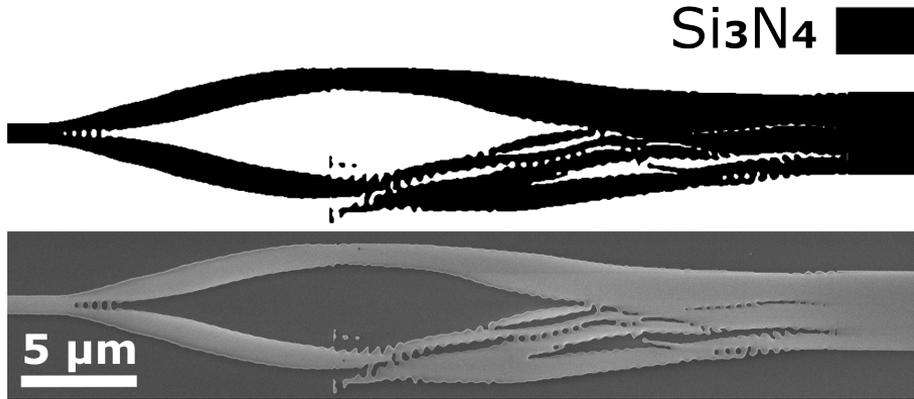


Electric field profile at 1550 nm:

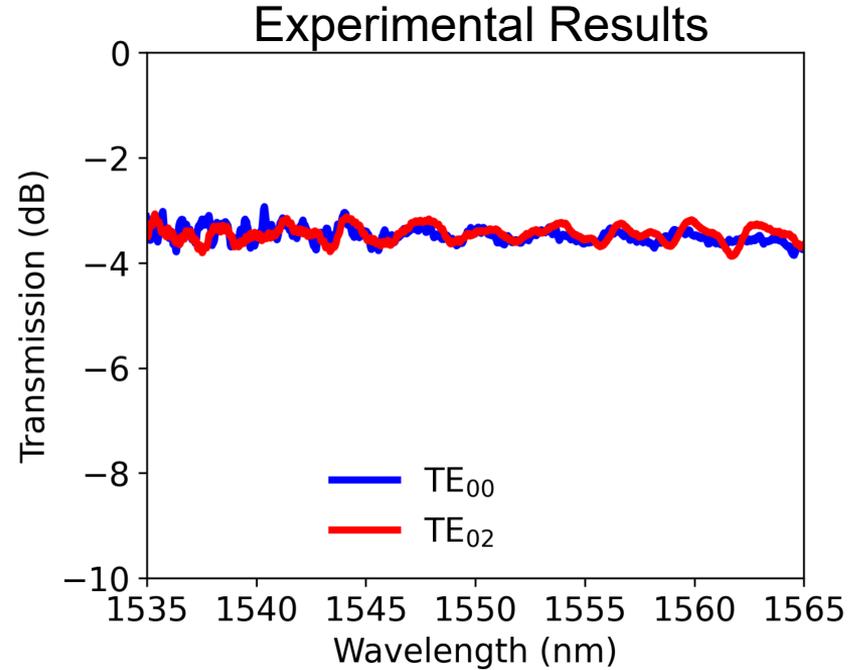
- a. Whole structure
- b. Beam splitter
- c. Mode converter: fundamental mode
- d. Mode converter : 2<sup>nd</sup> high order mode
- e. Mode converter : 3<sup>rd</sup> high order mode

# BiMC—Results

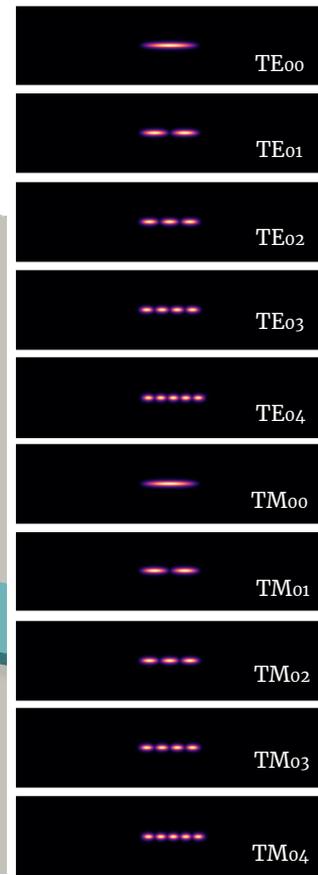
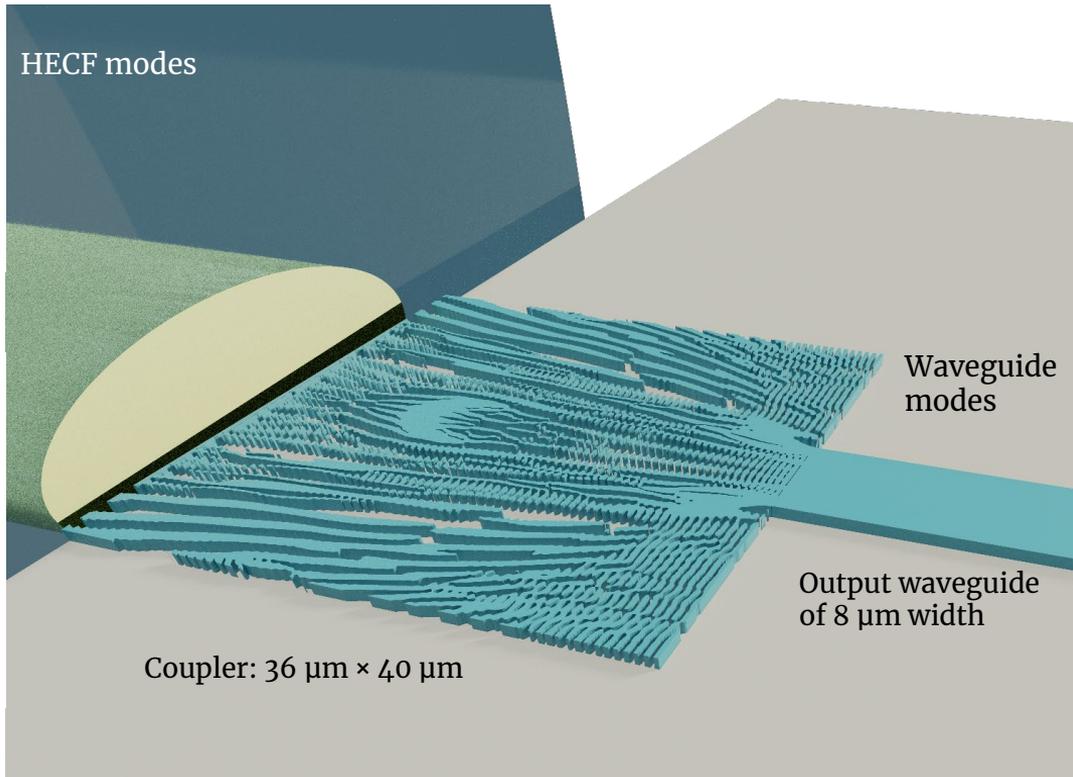
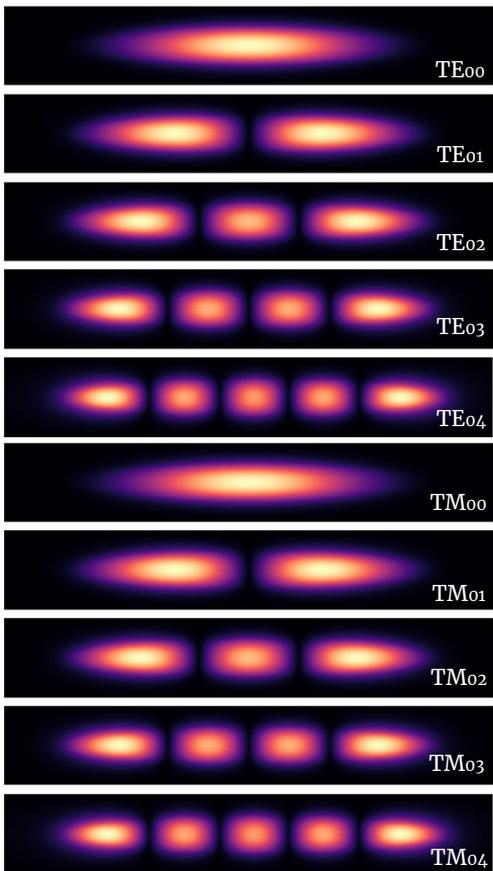
■ —● Results for BiMC  $TE_{00}$  :  $TE_{02}$



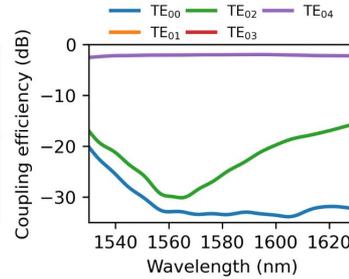
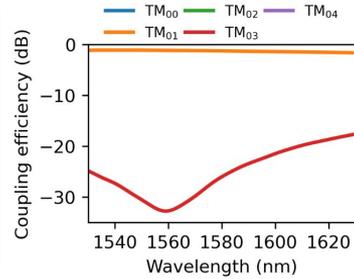
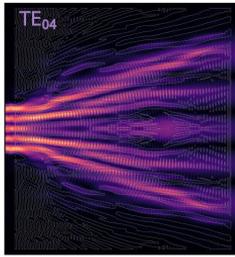
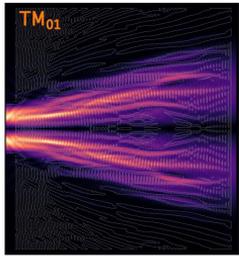
Average transmission	
$TE_{00}, TE_{02}$	-3.6 dB, -3.7 dB



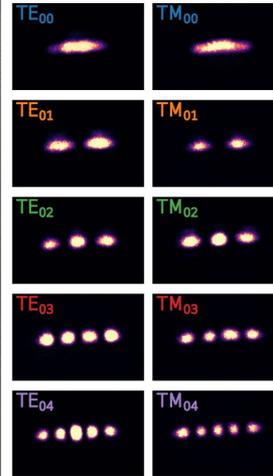
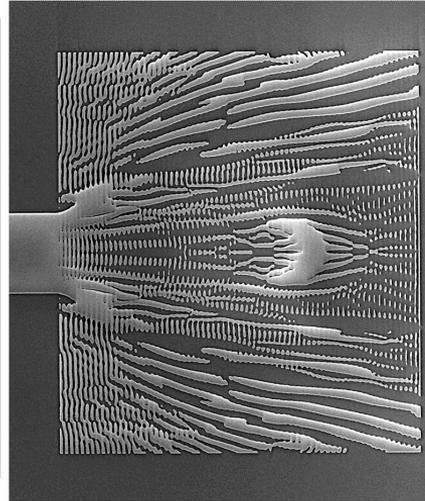
# 10-mode Fiber-to-chip Coupler



# 10-mode Fiber-to-chip Coupler—Simulations



TE <sub>00</sub>	-1.2	-194	-135	-141	-23.6	-204	-130	-145	-37.4	-189
TM <sub>00</sub>	-199	-1.1	-135	-143	-195	-23.7	-136	-142	-195	-24.2
TE <sub>01</sub>	-135	-138	-1.1	-187	-136	-140	-26.0	-196	-129	-138
TM <sub>01</sub>	-140	-140	-190	-1.1	-139	-138	-202	-30.8	-140	-132
TE <sub>02</sub>	-26.0	-214	-130	-135	-1.3	-187	-130	-144	-35.5	-185
TM <sub>02</sub>	-188	-25.0	-162	-132	-191	-1.2	-132	-129	-187	-20.8
TE <sub>03</sub>	-99	-130	-25.9	-188	-100	-142	-1.6	-181	-103	-132
TM <sub>03</sub>	-151	-100	-193	-30.1	-136	-101	-188	-1.3	-135	-104
TE <sub>04</sub>	-30.2	-156	-129	-130	-25.9	-164	-130	-125	-2.1	-178
TM <sub>04</sub>	-186	-24.8	-140	-134	-190	-22.2	-146	-131	-188	-1.5
	TE <sub>00</sub>	TM <sub>00</sub>	TE <sub>01</sub>	TM <sub>01</sub>	TE <sub>02</sub>	TM <sub>02</sub>	TE <sub>03</sub>	TM <sub>03</sub>	TE <sub>04</sub>	TM <sub>04</sub>



- Simulated efficiencies: **-1.1 to -2.1 dB**
- Modal crosstalk: **< -20 dB**
- Broadband response: Flat across the C-L bands.
- Measured profiles: Strong mode fidelity

- Topology optimization can be applied to SiN platforms
- Inverse design mitigates low index contrast limitations.
- In some cases, it can achieve Si-like compactness.
- What are the optimal parameters to get the best devices?



Le génie pour l'industrie

# Thank you for your attention!

Any questions?

[michael.menard@etsmtl.ca](mailto:michael.menard@etsmtl.ca)



**NSERC**  
**CRSNG**

**PRIMA**  
Les matériaux pour avancer



**CMC**  
MICROSYSTEMS

**IN**  
**RS**

Institut national  
de la recherche  
scientifique



**COPL**  
Centre d'optique,  
photonique et lasers